# **CHIPQUIK®**

## NC191SNL35T5

Datasheet revision 1.1 www.chipquik.com

### Smooth Flow™ Solder Paste No-Clean Sn96.5/Ag3.0/Cu0.5 T4 (35g Syringe)

#### **Product Highlights**

Smooth Flow<sup>™</sup> Technology

A lower density flux vehicle for better shear spread and improved flow during heating

Printing speeds up to 125mm/sec Long stencil life, Wide process window Halogen Free (EN14582 test method) Clear residue
Low voiding
Excellent wetting compatibility on most board finishes
Dispense grade
Compatible with enclosed print heads
RoHS 3 and REACH compliant

#### **Specifications**

Alloy: Sn96.5/Ag3.0/Cu0.5

Mesh Size: T5
Micron (µm) Range: 15-25

Flux Type: Synthetic No-Clean

Flux Classification: ROL0

Metal Load: 85.75% Metal by Weight Melting Point: 217-220°C (423-428°F) Packaging: 10cc/35g Syringe

Shelf Life: Refrigerated >6 months, Unrefrigerated >2 months \*See notes below:

\*Shelf Life Notes: Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using Made in USA high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

#### **Printer Operation**

Print Speed: 25-125mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

#### **Stencil Life**

>8 hours @ 20-50% RH 22-28°C (72-82°F) >4 hours @ 50-70% RH 22-28°C (72-82°F)

#### **Stencil Cleaning**

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

#### Storage and Handling

Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

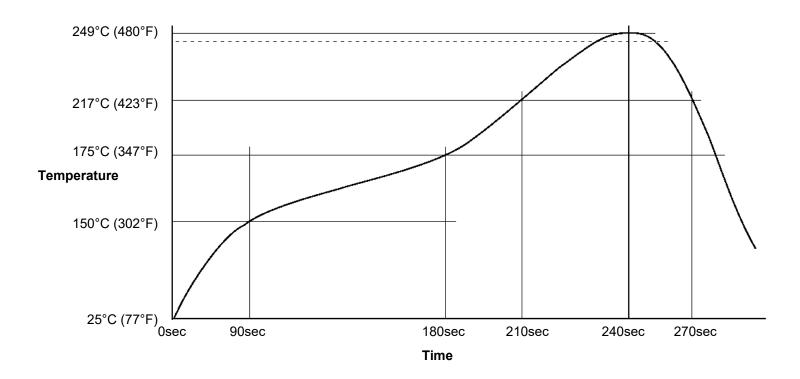
#### **Transportation**

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.



#### **Recommended Profile**

Reflow profile for Sn96.5/Ag3.0/Cu0.5 solder assembly, designed as a starting point for process optimization.



#### **Test Results**

Test Requirement	Result
	- Nesalt -
IPC-TM-650: 2.3.32	L: No breakthrough
IPC-TM-650: 2.6.15	L: No corrosion
IPC-TM-650: 2.3.28.1	L: <0.05%
IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
IPC-TM-650: 2.4.44	34g
IPC-TM-650: 2.4.34.4	Print: 130-185, Dispense: 105-150
IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Electronic Industry Citizenship Coalition (EICC)	Compliant
Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials
	IPC-TM-650: 2.6.15 IPC-TM-650: 2.3.28.1 IPC-TM-650: 2.6.14.1 IPC-TM-650: 2.6.3.7  IPC-TM-650: 2.4.44 IPC-TM-650: 2.4.34.4  IPC-TM-650: 3.4.2.5  Electronic Industry Citizenship Coalition (EICC)  Articles 33 and 67 of Regulation (EC)

#### **Conforms to the following Industry Standards:**

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes